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PATENT NUMBER and
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U.S. UTILITY Patent Application

10/018708

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**APPLICANTS: Okuda Yuji; Jimbo Naoyuki; Majima Kazutaka; Tsuji Masahiro; Takagi Hideki; Ishikawa Shigeharu; Yasuda Hiroyuki;					
**CONTINUING DATA VERIFIED: THIS APPLICATION IS A 371 OF PCT/JP00/03899 06/15/2000					
** FOREIGN APPLICATIONS VERIFIED: JAPAN 11/168522 06/15/1999 JAPAN 11/168523 06/15/1999 JAPAN 11/185333 06/30/1999					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed: <input type="checkbox"/> yes <input type="checkbox"/> no		35 USC 119 conditions met: <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO P3p2000078US/2369NP	
Verified and Acknowledged Examiners's initials					
TITLE : Table of wafer polisher, method of polishing wafer, and method of manufacturing semiconductor wafer					
U S DEPT OF COMM /PAT & TM-PTO-436L (Rev. 12-94)					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
Assistant Examiner		DRAWING	
ISSUE FEE		Sheets Drwg.	Figs. Drwg.
Amount Due	Date Paid	Print Fig.	
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
		PREPARED FOR ISSUE	
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